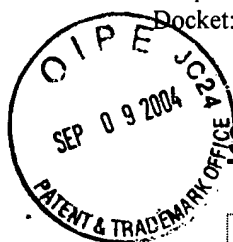


7 September 2004

Docket: 21295.73 (H5749US)

## Patent Application Data Sheet--Bibliographic Data

**Supplemental Application Data Sheet****Application Information**

Application Number::	not assigned
Filing Date::	not assigned
Application Type::	Regular
Subject Matter::	Utility
Suggested Classification::	
Suggested Group Art Unit::	
Title::	Method and Apparatus for Scanning a Semiconductor Wafer
Attorney Docket Number::	21295.73 (H5749US)
Request for Early Publication?::	No
Request for Non-Publication?::	No
Suggested Drawing Figure::	3
Total Drawing Sheets::	3
Small Entity?::	No
Licensed US Govt. Agency::	
Contract or Grant Numbers::	
Secrecy Order in Parent Appl.?::	

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**Representative Information**

**Patent Application Data Sheet--Bibliographic Data**

Representative Customer Number::	029127
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**Foreign Priority Information**

Country::	Application number::	Filing Date::	Priority Claimed::
Germany	DE10307358.2-52	02/21/2003	Yes

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